

RJK6020DPK

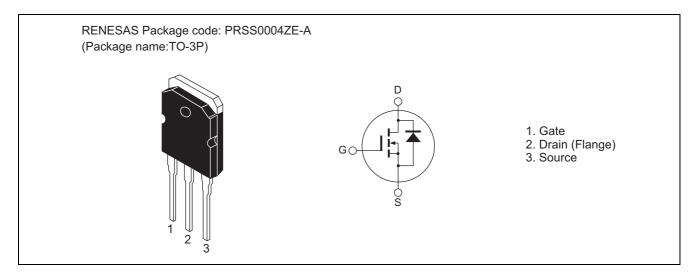
Silicon N Channel MOS FET High Speed Power Switching

REJ03G1465-0200 Rev.2.00 Sep 21, 2006

Features

- Low on-resistance
- Low leakage current
- High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	600	V	
Gate to source voltage	V _{GSS}	±30	V	
Drain current	I _D	32	А	
Drain peak current	I _{D (pulse)} Note1	96	А	
Body-drain diode reverse drain current	I _{DR}	32	А	
Body-drain diode reverse drain peak current	I _{DR} (pulse)	96	А	
Avalanche current	I _{AP} Note3	8.5	А	
Avalanche energy	E _{AR} Note3	3.9	mJ	
Channel dissipation	Pch Note2	200	W	
Channel to case thermal impedance	θch-c	0.625	°C/W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

- 2. Value at Tc = 25°C
- 3. STch = 25° C, Tch $\leq 150^{\circ}$ C

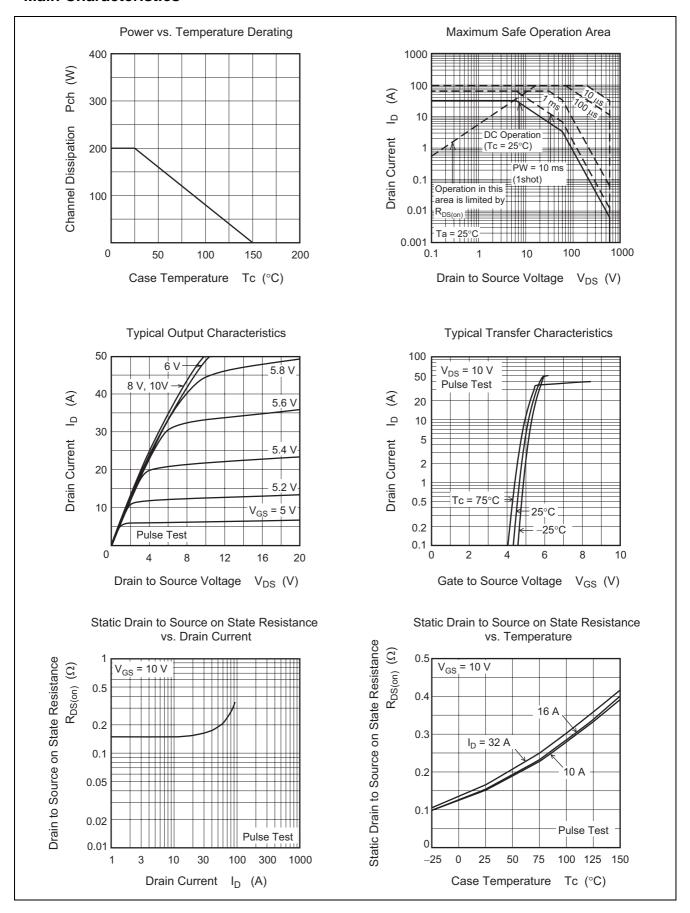
Electrical Characteristics

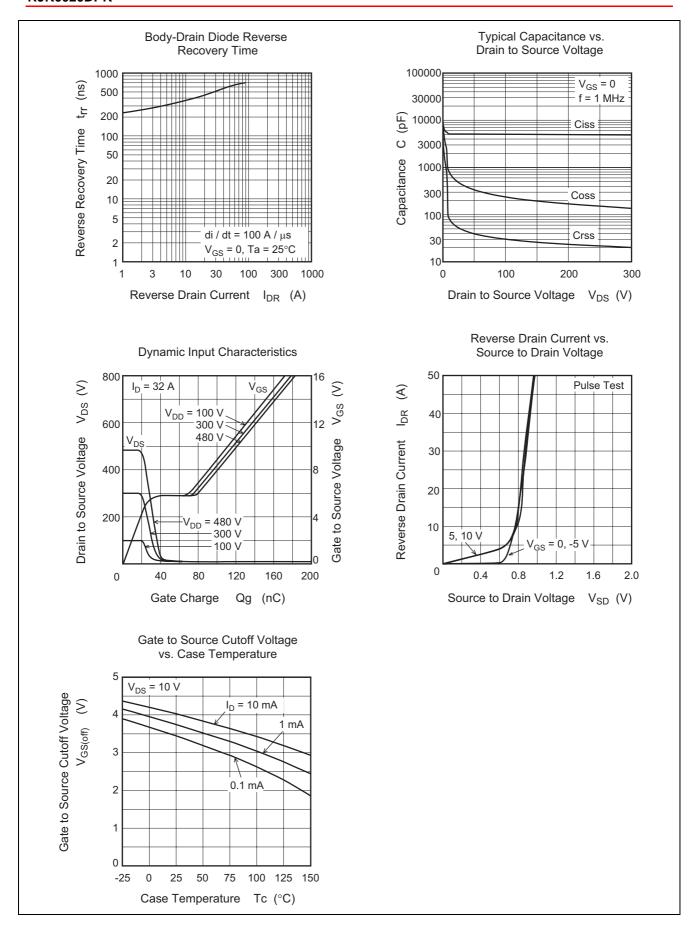
 $(Ta = 25^{\circ}C)$

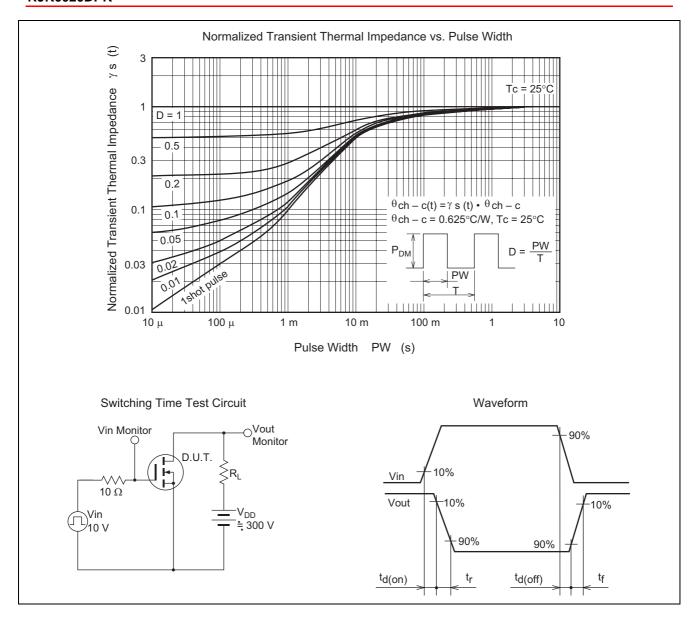
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	600	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I _{DSS}		_	1	μΑ	$V_{DS} = 600 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}		_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS(on)}	l	0.155	0.175	Ω	$I_D = 16 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$
Input capacitance	Ciss		5150		pF	V _{DS} = 25 V
Output capacitance	Coss	_	480	_	pF	V _{GS} = 0 f = 1 MHz
Reverse transfer capacitance	Crss	_	52	_	pF	
Turn-on delay time	t _{d(on)}	_	55	_	ns	I _D = 16 A
Rise time	t _r	_	100	_	ns	$V_{GS} = 10 \text{ V}$ $R_L = 18.8 \Omega$ $Rg = 10 \Omega$
Turn-off delay time	$t_{d(off)}$	_	176	_	ns	
Fall time	t _f	_	100	_	ns	
Total gate charge	Qg	_	121	_	nC	V _{DD} = 480 V
Gate to source charge	Qgs	_	28	_	nC	$V_{GS} = 10 \text{ V}$ $I_{D} = 32 \text{ A}$
Gate to drain charge	Qgd	_	50	_	nC	
Body-drain diode forward voltage	V_{DF}	_	0.88	1.50	V	$I_F = 32 \text{ A}, V_{GS} = 0^{\text{Note4}}$
Body-drain diode reverse recovery time	t _{rr}	1	520		ns	$I_F = 32 \text{ A}, V_{GS} = 0$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Notes: 4. Pulse test

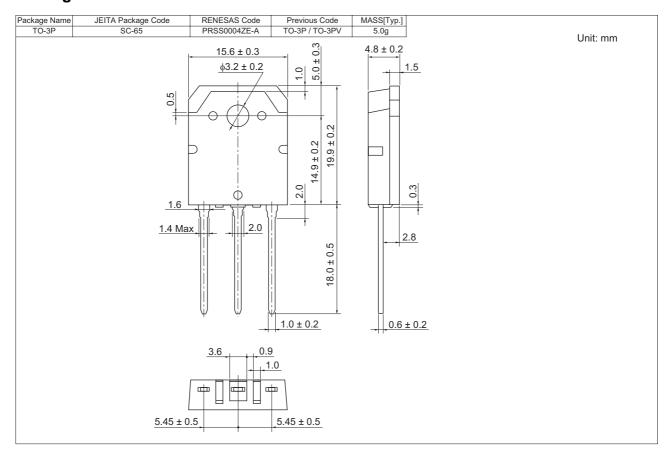
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
RJK6020DPK-00-T0	360 pcs	Box (Tube)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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